

1        **DECLARATION OF JOINT INVENTORS FOR PATENT APPLICATION**

2            As the below named inventor, I hereby declare that:

3            My residence, post office address and citizenship are as stated below  
4 next to my name.

5            I believe I am the original, first and joint inventor of the subject matter  
6 which is claimed and for which a patent is sought on the invention entitled:  
7 Plasma Enhanced Chemical Vapor Deposition Methods and Semiconductor  
8 Processing Methods of Forming Layers and Shallow Trench Isolation Regions,  
9 Serial No. 09/652,534, filed August 31, 2000.

10           I hereby state that I have reviewed and understand the contents of the  
11 above-identified specification, including the claims.

12           I acknowledge the duty to disclose information known to me to be  
13 material to patentability as defined in Title 37, Code of Federal Regulations  
14 §1.56.

15        **PRIOR FOREIGN APPLICATIONS:**

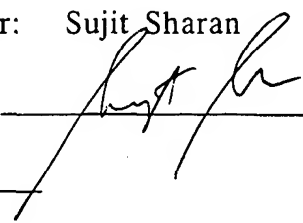
16           I hereby state that no applications for foreign patents or inventor's  
17 certificates have been filed prior to the date of execution of this declaration.

18           I hereby declare that all statements made herein of my own knowledge  
19 are true and that all statements made on information and belief are believed  
20 to be true; and further that these statements were made with the knowledge  
21 that willful false statements and the like so made are punishable by fine or  
22 imprisonment, or both, under Section 1001 of Title 18 of the United States

1 Code and that such willful false statement may jeopardize the validity of the  
2 application or any patent issued therefrom.

3 \* \* \* \* \*

4 Full name of inventor: Sujit Sharan

5 Inventor's Signature: 

6 Date: 1/9/01

7 Residence: Boise, Idaho

8 Citizenship: India

9 Post Office Address: 6258 South Survival Place, Boise, ID 83716

10 \* \* \* \* \*

11 Full name of inventor: Gurtej S. Sandhu

12 Inventor's Signature: \_\_\_\_\_

13 Date: \_\_\_\_\_

14 Residence: Boise, Idaho

15 Citizenship: United Kingdom

16 Post Office Address: 2964 East Parkriver Drive, Boise, ID 83706

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3 \* \* \* \* \*

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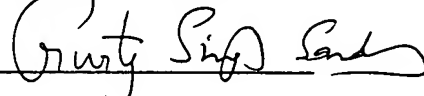
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